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24 stainless paiting ball for making IC Tin ball

Product ID: 658

Price: **10.41 EUR**

Product weight: **0.01 kg**

Description:

24 stainless paiting ball for making IC Tin ball is a needed tool when you have to exchange BGA parts of your phone.

Contact details:

Telefon: +48 17 227 00 25
Infolinia: 0 801 671 717
E-mail: biuro@multi-com.pl
Skype: Multi-COM

Address:

Multi-COM Sp. z o.o.
ul. Stanisława Krzaklewskiego 31b
36-100 Kolbuszowa
POLSKA

[Go to the product](#)

